

## SNx4LVC00A Quadruple 2-Input Positive-NAND Gates

### 1 Features

- Operate From 1.65 V to 3.6 V
- Specified From  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ ,  $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ , and  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$
- Inputs Accept Voltages to 5.5 V
- Max  $t_{pd}$  of 4.3 ns at 3.3 V
- Typical  $V_{OLP}$  (Output Ground Bounce)  $< 0.8$  V at  $V_{CC} = 3.3$  V,  $T_A = 25^{\circ}\text{C}$
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot)  $> 2$  V at  $V_{CC} = 3.3$  V,  $T_A = 25^{\circ}\text{C}$
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- On Products Compliant to MIL-PRF-38535, All Parameters Are Tested Unless Otherwise Noted. On All Other Products, Production Processing Does Not Necessarily Include Testing of All Parameters.
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model
  - 200-V Machine Model
  - 1000-V Charged-Device Model

### 2 Applications

- AV Receivers
- Audio Docks: Portable
- Blu-ray Players and Home Theater
- MP3 Players or Recorders
- Personal Digital Assistants (PDAs)
- Power: Telecom/Server AC/DC Supply: Single Controller: Analog and Digital
- Solid State Drives (SSDs): Client and Enterprise
- TVs: LCD, Digital, and High-Definition (HDTV)
- Tablets: Enterprise
- Video Analytics: Server
- Wireless Headsets, Keyboards, and Mice

### 3 Description

The SN54LVC00A quadruple 2-input positive-NAND gate is designed for 2.7-V to 3.6-V  $V_{CC}$  operation, and the SN74LVC00A quadruple 2-input positive-NAND gate is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

The SNx4LVC00A devices perform the Boolean function  $Y = A \times B$  or  $Y = \bar{A} + \bar{B}$  in positive logic.

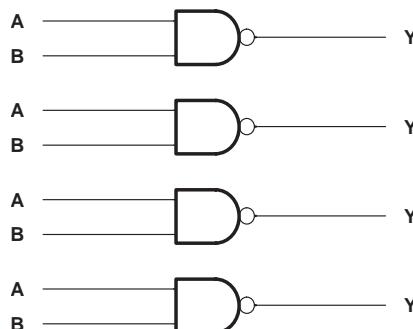
Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SNx4LVC00A	SOIC (14)	8.65 mm $\times$ 3.91 mm
	SSOP (14)	6.20 mm $\times$ 5.30 mm
	SOP (14)	10.30 mm $\times$ 5.30 mm
	TSSOP (14)	5.00 mm $\times$ 4.40 mm
	VQFN (14)	3.50 mm $\times$ 3.50 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

### 4 Simplified Schematic



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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## 5 Revision History

### Changes from Revision Q (December 2014) to Revision R

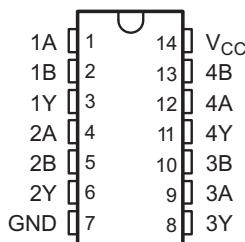
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•	Added Junction temperature row to <i>Absolute Maximum Ratings</i> table .....	4
•	Changed statement of "open drain" to "maximum sink and source current" statement in Overview of <i>Detailed Description</i> section .....	9
•	Deleted "open drain" from <i>Application Information</i> section .....	10

### Changes from Revision P (July 2005) to Revision Q

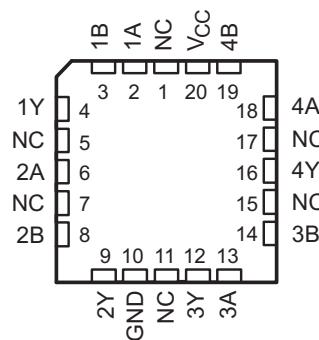
		Page
•	Added <i>Applications</i> , <i>Device Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Typical Characteristics</i> , <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....	1
•	Deleted <i>Ordering Information</i> table .....	1
•	Added Military Disclaimer to <i>Features</i> .....	1

## 6 Pin Configuration and Functions

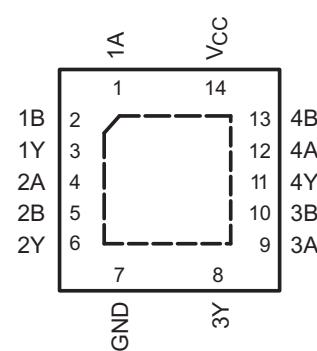
**SN54LVC00A... J OR W PACKAGE  
SN74LVC00A... D, DB, NS, OR PW PACKAGE  
(TOP VIEW)**



**SN54LVC00A... FK PACKAGE  
(TOP VIEW)**



**SN74LVC00A... RGY PACKAGE  
(TOP VIEW)**



NC - No internal connection

### Pin Functions

NAME	PIN				TYPE	DESCRIPTION		
	SN74LVC00A		SN54LVC00A					
	D, DB, NS, PW	RGY	J, W	FK				
1A	1	1	1	2	I	Gate 1 input		
1B	2	2	2	3	I	Gate 1 input		
1Y	3	3	3	4	O	Gate 1 output		
2A	4	4	4	6	I	Gate 2 input		
2B	5	5	5	8	I	Gate 2 input		
2Y	6	6	6	9	O	Gate 2 output		
GND	7	7	7	10	—	Ground Pin		
3Y	8	8	8	12	—	Power Pin		
3A	9	9	9	13	I	Gate 4 input		
3B	10	10	10	14	I	Gate 4 input		
4Y	11	11	11	16	O	Gate 4 output		
4A	12	12	12	18	I	Gate 3 input		
4B	13	13	13	19	I	Gate 3 input		
V <sub>CC</sub>	14	14	14	20	O	Gate 3 output		
NC	—	—	—	1 5 7 11 15 17	—	No Connection		

## 7 Specifications

### 7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	–0.5	6.5	V
$V_I$	Input voltage range <sup>(2)</sup>	–0.5	6.5	V
$V_O$	Output voltage range <sup>(2)(3)</sup>	–0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current $V_I < 0$		–50	mA
$I_{OK}$	Output clamp current $V_O < 0$		–50	mA
$I_O$	Continuous output current		$\pm 50$	mA
$V_{CC}$	Continuous current through GND		$\pm 100$	mA
$P_{tot}$	Power dissipation <sup>(4)(5)</sup> $T_A = -40^\circ\text{C}$ to $125^\circ\text{C}$		500	mW
$T_{stg}$	Storage temperature range	–65	150	$^\circ\text{C}$
$T_j$	Junction Temperature		150	$^\circ\text{C}$

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of  $V_{CC}$  is provided in the *Recommended Operating Conditions* table.
- (4) For the D package: above  $70^\circ\text{C}$ , the value of  $P_{tot}$  derates linearly with 8 mW/K.
- (5) For the DB, NS, and PW packages: above  $60^\circ\text{C}$ , the value of  $P_{tot}$  derates linearly with 5.5 mW/K.

### 7.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	2000
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 7.3 Recommended Operating Conditions, SN54LVC00A

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

				<b>SN54LVC00A</b>	<b>UNIT</b>
				<b>–55°C to 125°C</b>	
				<b>MIN</b> <b>MAX</b>	
$V_{CC}$	Supply voltage		Operating	2   3.6	<b>V</b>
			Data retention only	1.5	
$V_{IH}$	High-level input voltage		$V_{CC} = 2.7\text{ V}$ to $3.6\text{ V}$	2	<b>V</b>
$V_{IL}$	Low-level input voltage		$V_{CC} = 2.7\text{ V}$ to $3.6\text{ V}$	0.8	<b>V</b>
$V_I$	Input voltage			0   5.5	<b>V</b>
$V_O$	Output voltage			0 $V_{CC}$	<b>V</b>
$I_{OH}$	High-level output current		$V_{CC} = 2.7\text{ V}$	–12	<b>mA</b>
			$V_{CC} = 3\text{ V}$	–24	
$I_{OL}$	Low-level output current		$V_{CC} = 2.7\text{ V}$	12	<b>mA</b>
			$V_{CC} = 3\text{ V}$	24	

(1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

### 7.4 Recommended Operating Conditions, SN74LVC00A

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		<b>SN74LVC00A</b>						<b>UNIT</b>	
		$T_A = 25^\circ\text{C}$		$–40^\circ\text{C}$ to $85^\circ\text{C}$		$–40^\circ\text{C}$ to $125^\circ\text{C}$			
		<b>MIN</b>	<b>MAX</b>	<b>MIN</b>	<b>MAX</b>	<b>MIN</b>	<b>MAX</b>		
$V_{CC}$	Supply voltage		Operating	1.65	3.6	1.65	3.6	<b>V</b>	
			Data retention only	1.5		1.5			
$V_{IH}$	High-level input voltage	$V_{CC} = 1.65\text{ V}$ to $1.95\text{ V}$	$0.65 \times V_{CC}$	$0.65 \times V_{CC}$		$0.65 \times V_{CC}$		<b>V</b>	
		$V_{CC} = 2.3\text{ V}$ to $2.7\text{ V}$	1.7		1.7		1.7		
		$V_{CC} = 2.7\text{ V}$ to $3.6\text{ V}$	2		2		2		
$V_{IL}$	Low-level input voltage	$V_{CC} = 1.65\text{ V}$ to $1.95\text{ V}$	$0.35 \times V_{CC}$	$0.35 \times V_{CC}$		$0.35 \times V_{CC}$		<b>V</b>	
		$V_{CC} = 2.3\text{ V}$ to $2.7\text{ V}$	0.7		0.7		0.7		
		$V_{CC} = 2.7\text{ V}$ to $3.6\text{ V}$	0.8		0.8		0.8		
$V_I$	Input voltage		0	5.5	0	5.5	0	5.5	
$V_O$	Output voltage		0	$V_{CC}$	0	$V_{CC}$	0	$V_{CC}$	
$I_{OH}$	High-level output current	$V_{CC} = 1.65\text{ V}$	–4		–4		–4	<b>mA</b>	
		$V_{CC} = 2.3\text{ V}$	–8		–8		–8		
		$V_{CC} = 2.7\text{ V}$	–12		–12		–12		
		$V_{CC} = 3\text{ V}$	–24		–24		–24		
$I_{OL}$	Low-level output current	$V_{CC} = 1.65\text{ V}$	4		4		4	<b>mA</b>	
		$V_{CC} = 2.3\text{ V}$	8		8		8		
		$V_{CC} = 2.7\text{ V}$	12		12		12		
		$V_{CC} = 3\text{ V}$	24		24		24		

(1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

## 7.5 Thermal Information

THERMAL METRIC <sup>(1)</sup>	SN74LVC00A					UNIT
	D	DB	NS	PW	RGY	
	14 PINS	14 PINS	14 PINS	14 PINS	14 PINS	
R <sub>θJA</sub> Junction-to-ambient thermal resistance	86	96	76	113	47	°C/W

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

## 7.6 Electrical Characteristics, SN54LVC00A

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	SN54LVC00A		UNIT	
			−55°C to 125°C			
			MIN	MAX		
V <sub>OH</sub>	I <sub>OH</sub> = −100 µA	2.7 V to 3.6 V	V <sub>CC</sub> − 0.2		V	
	I <sub>OH</sub> = −12 mA	2.7 V	2.2			
	I <sub>OH</sub> = −24 mA	3 V	2.4			
V <sub>OL</sub>	I <sub>OL</sub> = 100 µA	2.7 V to 3.6 V	0.2		V	
	I <sub>OL</sub> = 12 mA	2.7 V	0.4			
	I <sub>OL</sub> = 24 mA	3 V	0.55			
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	3.6 V	±5	µA		
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V	10	µA		
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> − 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V	500	µA		

## 7.7 Electrical Characteristics, SN74LVC00A

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	SN74LVC00A						UNIT	
			T <sub>A</sub> = 25°C			−40°C to 85°C		−40°C to 125°C		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = −100 µA	1.65 V to 3.6 V	V <sub>CC</sub> − 0.2			V <sub>CC</sub> − 0.2		V <sub>CC</sub> − 0.3		V
	I <sub>OH</sub> = −4 mA	1.65 V	1.29			1.2		1.05		
	I <sub>OH</sub> = −8 mA	2.3 V	1.9			1.7		1.55		
	I <sub>OH</sub> = −12 mA	2.7 V	2.2			2.2		2.05		
		3 V	2.4			2.4		2.25		
	I <sub>OH</sub> = −24 mA	3 V	2.3			2.2		2		
V <sub>OL</sub>	I <sub>OL</sub> = 100 µA	1.65 V to 3.6 V		0.1		0.2		0.3		V
	I <sub>OL</sub> = 4 mA	1.65 V		0.24		0.45		0.6		
	I <sub>OL</sub> = 8 mA	2.3 V		0.3		0.7		0.85		
	I <sub>OL</sub> = 12 mA	2.7 V		0.4		0.4		0.6		
	I <sub>OL</sub> = 24 mA	3 V		0.55		0.55		0.8		
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	3.6 V		±1		±5		±20	µA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V		1		10		40	µA	
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> − 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V		500		500		5000	µA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		5					pF	

## 7.8 Switching Characteristics, SN54LVC00A

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 2](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	SN54LVC00A		UNIT	
				-55°C to 125°C			
				MIN	MAX		
t <sub>pd</sub>	A or B	Y	2.7 V		5.1	ns	
				3.3 V ± 0.3 V	1		

## 7.9 Switching Characteristics, SN74LVC00A

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 2](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	SN74LVC00A						UNIT	
				T <sub>A</sub> = 25°C			-40°C to 85°C		-40°C to 125°C		
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	Y	1.8 V ± 0.15 V	1	6	12	1	12.5	1	14	ns
			2.5 V ± 0.2 V	1	4.6	5.9	1	6.4	1	7.9	
			2.7 V	1	4.3	4.9	1	5.1	1	6.5	
			3.3 V ± 0.3 V	1	3.5	4.1	1	4.3	1	5.5	
t <sub>sk(o)</sub>			3.3 V ± 0.3 V				1		1	1.5	ns

## 7.10 Operating Characteristics

T<sub>A</sub> = 25°C

C <sub>pd</sub>	Power dissipation capacitance per gate	f = 10 MHz	TEST CONDITIONS	V <sub>CC</sub>	TYP	UNIT
				1.8 V	18	pF
				2.5 V	18	
				3.3 V	19	

## 7.11 Typical Characteristics

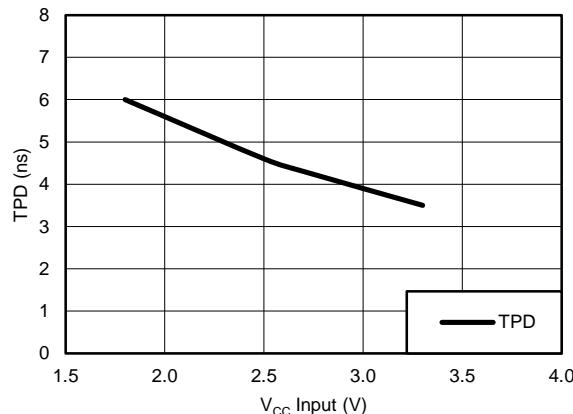
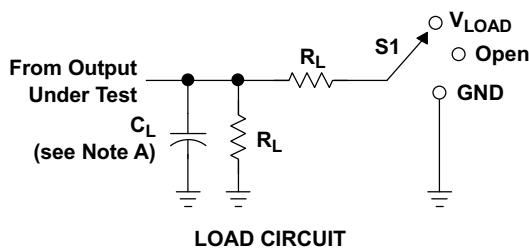


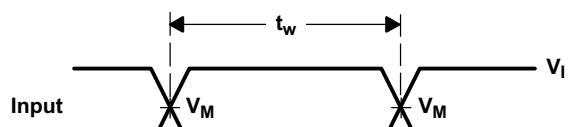
Figure 1. TPD vs V<sub>CC</sub> (T<sub>A</sub> = 25°C)

## 8 Parameter Measurement Information

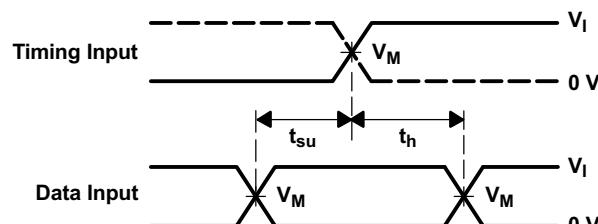


TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

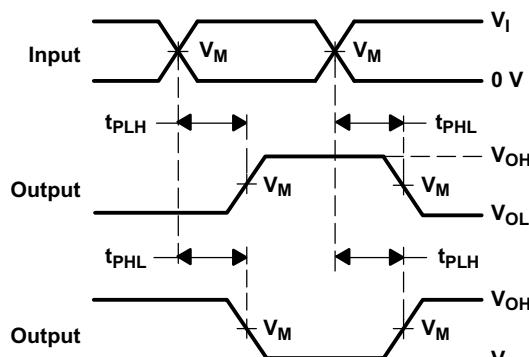
$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_\Delta$
	$V_I$	$t_r/t_f$					
$1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC}$	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC}$	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
2.7 V	2.7 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$3.3 \text{ V} \pm 0.3 \text{ V}$	2.7 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



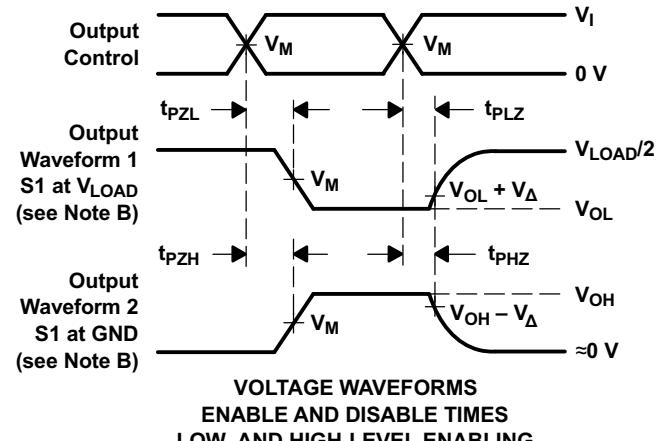
VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

NOTES:

- $C_L$  includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ .
- The outputs are measured one at a time, with one transition per measurement.
- $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms

## 9 Detailed Description

### 9.1 Overview

The maximum sink and source current is 24mA.

Inputs can be driven from 1.8-V, 2.5-V, 3.3-V (LVTTL), or 5-V (CMOS) devices. This feature allows the use of this device as translators in a mixed-system environment.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

### 9.2 Functional Block Diagram

**Logic Diagram, Each Gate (Positive Logic)**



### 9.3 Feature Description

- Wide operating voltage range
  - Operates from 1.65 V to 3.6 V
- Allows up or down voltage translation
  - Inputs and outputs accept voltages to 5.5 V
- $I_{off}$  feature
  - Allows voltages on the inputs and outputs when  $V_{CC}$  is 0 V

### 9.4 Device Functional Modes

**Table 1. Function Table  
(Each Gate)**

INPUTS		OUTPUT Y
A	B	
H	H	L
L	X	H
X	L	H

## 10 Application and Implementation

### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 10.1 Application Information

SN74LVC00A is a high-drive CMOS device that can be used for a multitude of buffer-type functions. It can produce 24 mA of drive current at 3.3 V. Therefore, this device is ideal for driving multiple inputs and for high-speed applications up to 100 MHz. The inputs and outputs are 5.5-V tolerant allowing the device to translate up to 5.5 V or down to  $V_{CC}$ .

### 10.2 Typical Application

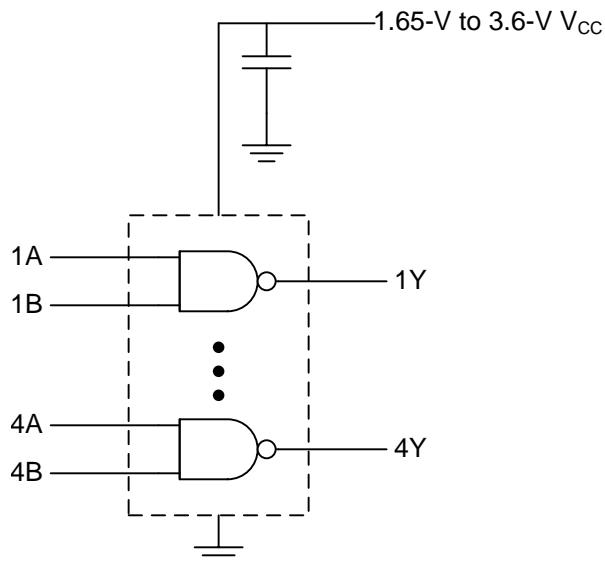


Figure 3. Typical NAND Gate Application and Supply Voltage

#### 10.2.1 Design Requirements

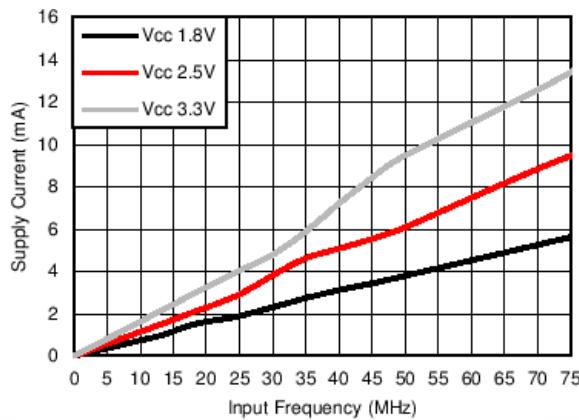
This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads; therefore, routing and load conditions should be considered to prevent ringing.

#### 10.2.2 Detailed Design Procedure

1. Recommended Input Conditions
  - Rise time and fall time specs: See  $(\Delta t/\Delta V)$  in the *Recommended Operating Conditions, SN74LVC00A* table.
  - Specified high and low levels: See  $(V_{IH}$  and  $V_{IL}$ ) in the *Recommended Operating Conditions, SN74LVC00A* table.
  - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid  $V_{CC}$ .
2. Recommend Output Conditions
  - Load currents should not exceed 25 mA per output and 50 mA total for the part.
  - Outputs should not be pulled above 5.5 V.

## Typical Application (continued)

### 10.2.3 Application Curves



**Figure 4. I<sub>cc</sub> vs Frequency**

## 11 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [Recommended Operating Conditions, SN74LVC00A](#) table.

Each V<sub>CC</sub> pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1  $\mu$ F is recommended; if there are multiple V<sub>CC</sub> pins, then 0.01  $\mu$ F or 0.022  $\mu$ F is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1  $\mu$ F and a 1  $\mu$ F are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

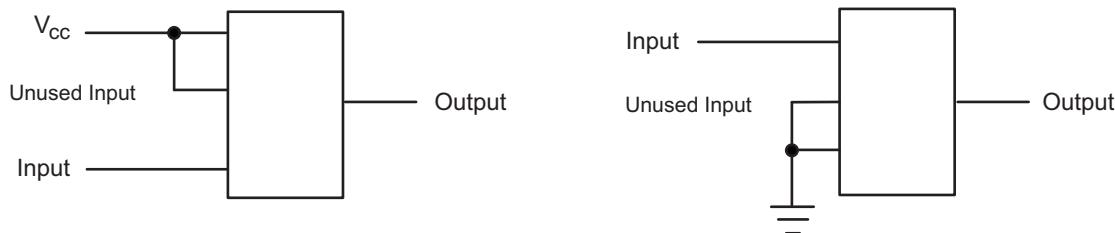
## 12 Layout

### 12.1 Layout Guidelines

When using multiple bit logic devices inputs should never float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. [Layout Example](#) specifies the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V<sub>CC</sub>, whichever makes more sense or is more convenient. It is generally acceptable to float outputs, unless the part is a transceiver.

### 12.2 Layout Example



**Figure 5. Layout Diagram**

## 13 Device and Documentation Support

### 13.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**Table 2. Related Links**

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54LVC00A	<a href="#">Click here</a>				
SN74LVC00A	<a href="#">Click here</a>				

### 13.2 Trademarks

All trademarks are the property of their respective owners.

### 13.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 13.4 Glossary

#### [SLYZ022 — TI Glossary](#)

This glossary lists and explains terms, acronyms, and definitions.

## 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9753301Q2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9753301Q2A SNJ54LVC 00AFK	<a href="#">Samples</a>
5962-9753301QCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9753301QC A SNJ54LVC00AJ	<a href="#">Samples</a>
5962-9753301QDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9753301QD A SNJ54LVC00AW	<a href="#">Samples</a>
5962-9753301VDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9753301VD A SNV54LVC00AW	<a href="#">Samples</a>
SN74LVC00AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC00A	<a href="#">Samples</a>
SN74LVC00ADBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC00A	<a href="#">Samples</a>
SN74LVC00ADBRG4	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC00A	<a href="#">Samples</a>
SN74LVC00ADE4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC00A	<a href="#">Samples</a>
SN74LVC00ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC00A	<a href="#">Samples</a>
SN74LVC00ADRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC00A	<a href="#">Samples</a>
SN74LVC00ADT	ACTIVE	SOIC	D	14	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC00A	<a href="#">Samples</a>
SN74LVC00ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC00A	<a href="#">Samples</a>
SN74LVC00ANSRG4	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC00A	<a href="#">Samples</a>
SN74LVC00APW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC00A	<a href="#">Samples</a>
SN74LVC00APWE4	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC00A	<a href="#">Samples</a>
SN74LVC00APWG4	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC00A	<a href="#">Samples</a>
SN74LVC00APWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	LC00A	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC00APWRE4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC00A	<a href="#">Samples</a>
SN74LVC00APWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC00A	<a href="#">Samples</a>
SN74LVC00APWT	ACTIVE	TSSOP	PW	14	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC00A	<a href="#">Samples</a>
SN74LVC00ARGYR	ACTIVE	VQFN	RGY	14	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LC00A	<a href="#">Samples</a>
SNJ54LVC00AFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9753301Q2A SNJ54LVC00AFK	<a href="#">Samples</a>
SNJ54LVC00AJ	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9753301QC A SNJ54LVC00AJ	<a href="#">Samples</a>
SNJ54LVC00AW	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9753301QD A SNJ54LVC00AW	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

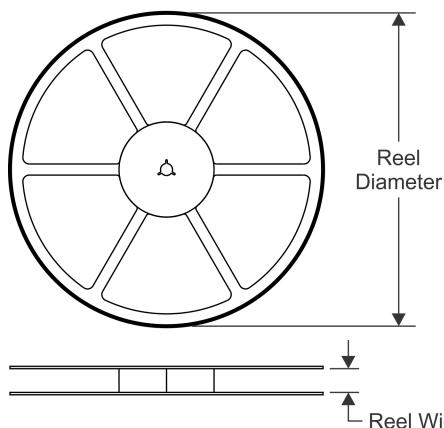
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN54LVC00A, SN54LVC00A-SP, SN74LVC00A :**

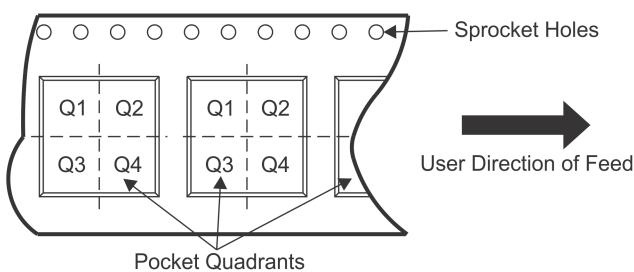
- Catalog : [SN74LVC00A](#), [SN54LVC00A](#)
- Automotive : [SN74LVC00A-Q1](#), [SN74LVC00A-Q1](#)
- Enhanced Product : [SN74LVC00A-EP](#), [SN74LVC00A-EP](#)
- Military : [SN54LVC00A](#)
- Space : [SN54LVC00A-SP](#)

**NOTE: Qualified Version Definitions:**

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

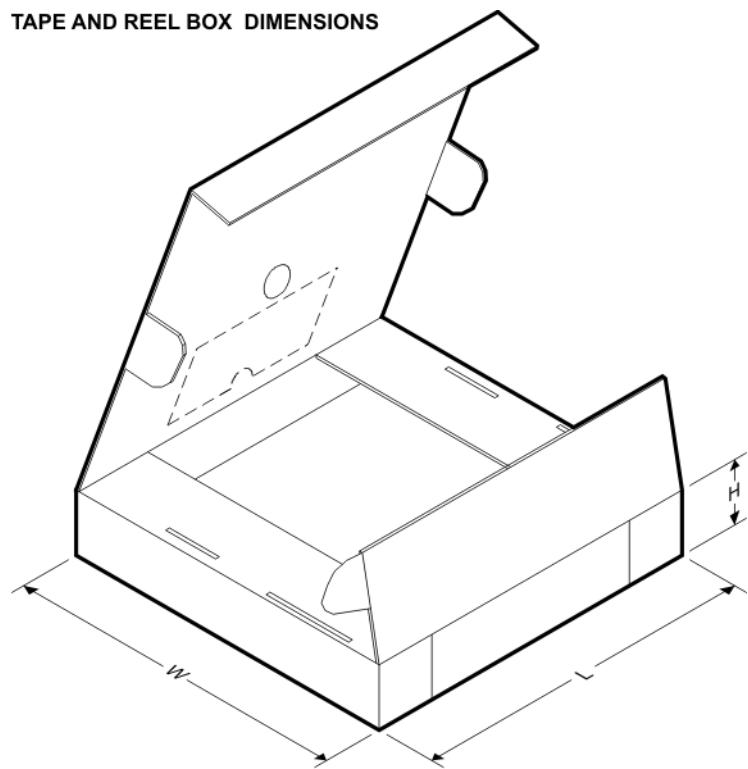
**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


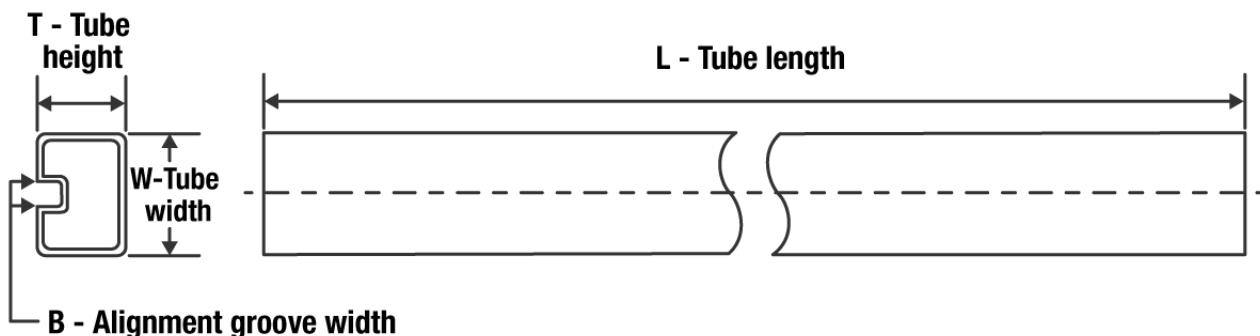
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC00ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LVC00ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVC00ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVC00ADT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVC00ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LVC00APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC00APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC00APWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC00APWT	TSSOP	PW	14	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC00ARGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC00ADBR	SSOP	DB	14	2000	853.0	449.0	35.0
SN74LVC00ADR	SOIC	D	14	2500	340.5	336.1	32.0
SN74LVC00ADR	SOIC	D	14	2500	853.0	449.0	35.0
SN74LVC00ADT	SOIC	D	14	250	210.0	185.0	35.0
SN74LVC00ANSR	SO	NS	14	2000	853.0	449.0	35.0
SN74LVC00APWR	TSSOP	PW	14	2000	364.0	364.0	27.0
SN74LVC00APWR	TSSOP	PW	14	2000	853.0	449.0	35.0
SN74LVC00APWRG4	TSSOP	PW	14	2000	853.0	449.0	35.0
SN74LVC00APWT	TSSOP	PW	14	250	853.0	449.0	35.0
SN74LVC00ARGYR	VQFN	RGY	14	3000	853.0	449.0	35.0

**TUBE**


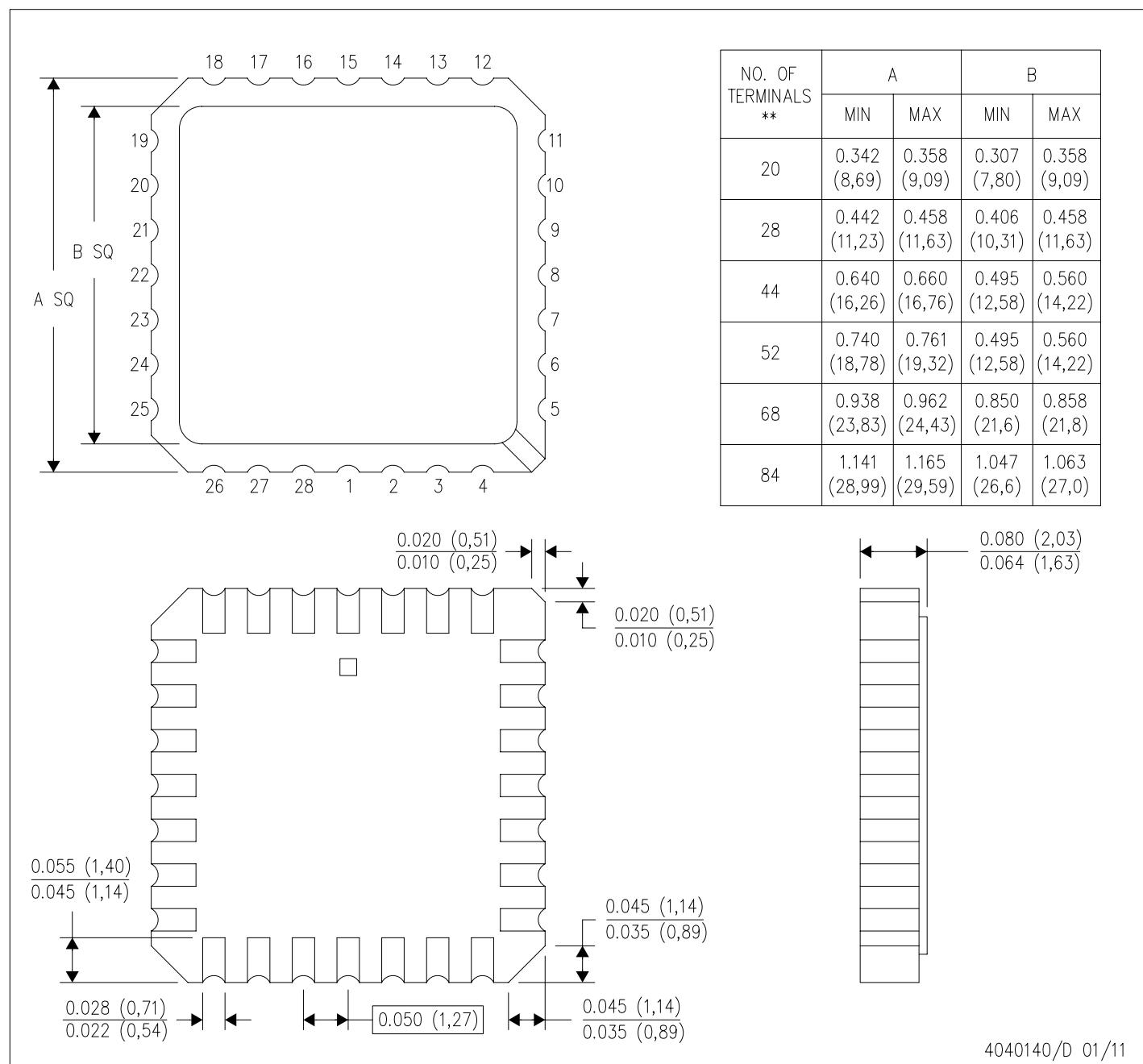
\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9753301Q2A	FK	LCCC	20	1	506.98	12.06	2030	NA
5962-9753301VDA	W	CFP	14	1	506.98	26.16	6220	NA
SN74LVC00AD	D	SOIC	14	50	506.6	8	3940	4.32
SN74LVC00ADE4	D	SOIC	14	50	506.6	8	3940	4.32
SN74LVC00APW	PW	TSSOP	14	90	530	10.2	3600	3.5
SN74LVC00APWE4	PW	TSSOP	14	90	530	10.2	3600	3.5
SN74LVC00APWG4	PW	TSSOP	14	90	530	10.2	3600	3.5
SNJ54LVC00AFK	FK	LCCC	20	1	506.98	12.06	2030	NA

FK (S-CQCC-N\*\*)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES:

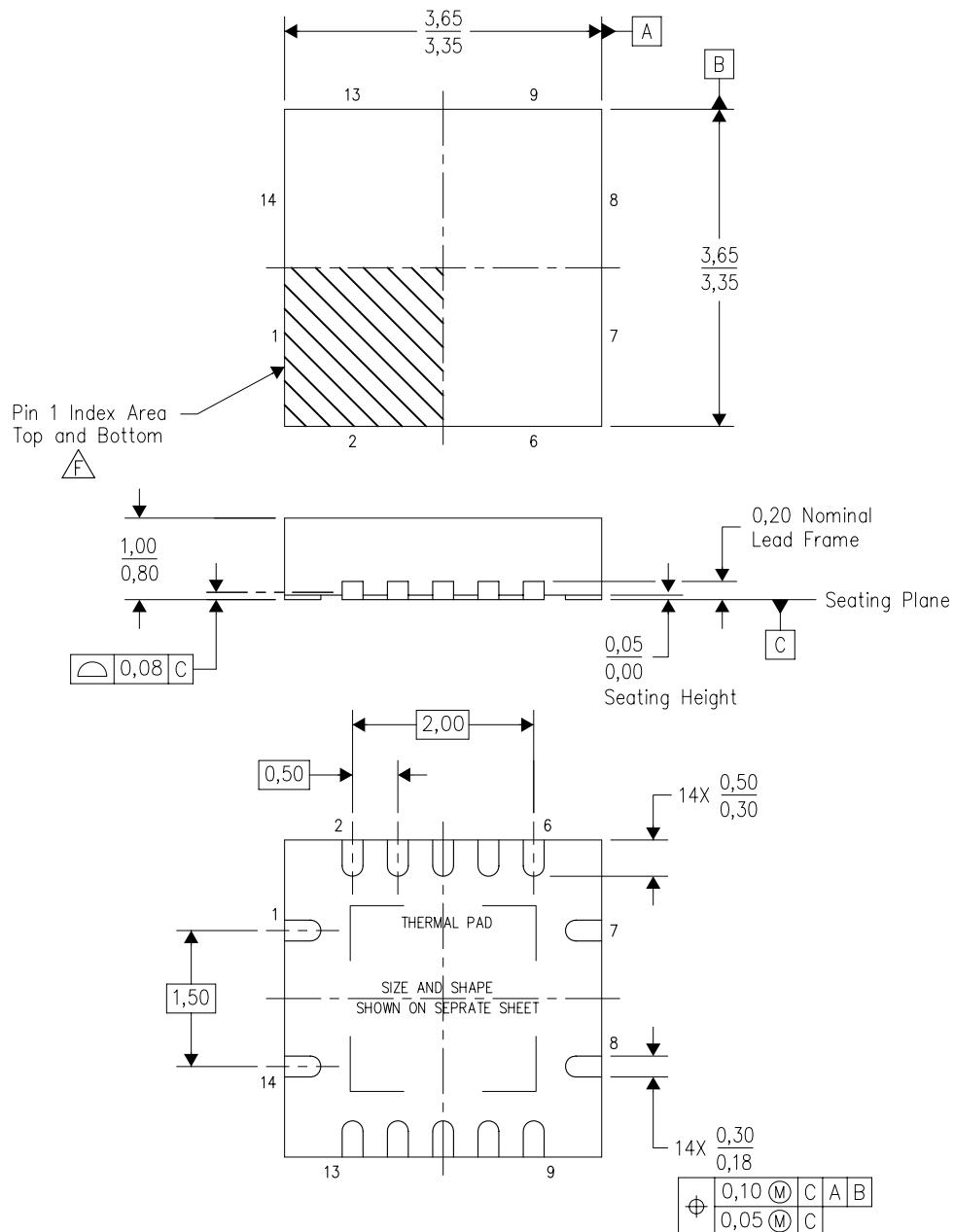
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004

4040140/D 01/11

## MECHANICAL DATA

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



Bottom View

4203539-2/l 06/2011

NOTES:

- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- QFN (Quad Flatpack No-Lead) package configuration.
- The package thermal pad must be soldered to the board for thermal and mechanical performance.
- See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- Package complies to JEDEC MO-241 variation BA.

# THERMAL PAD MECHANICAL DATA

RGY (S-PVQFN-N14)

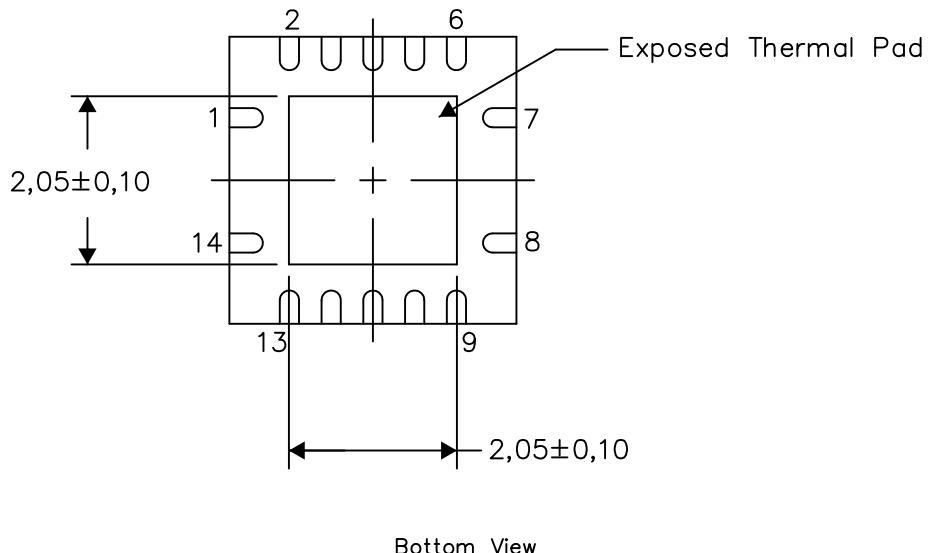
PLASTIC QUAD FLATPACK NO-LEAD

## THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

Exposed Thermal Pad Dimensions

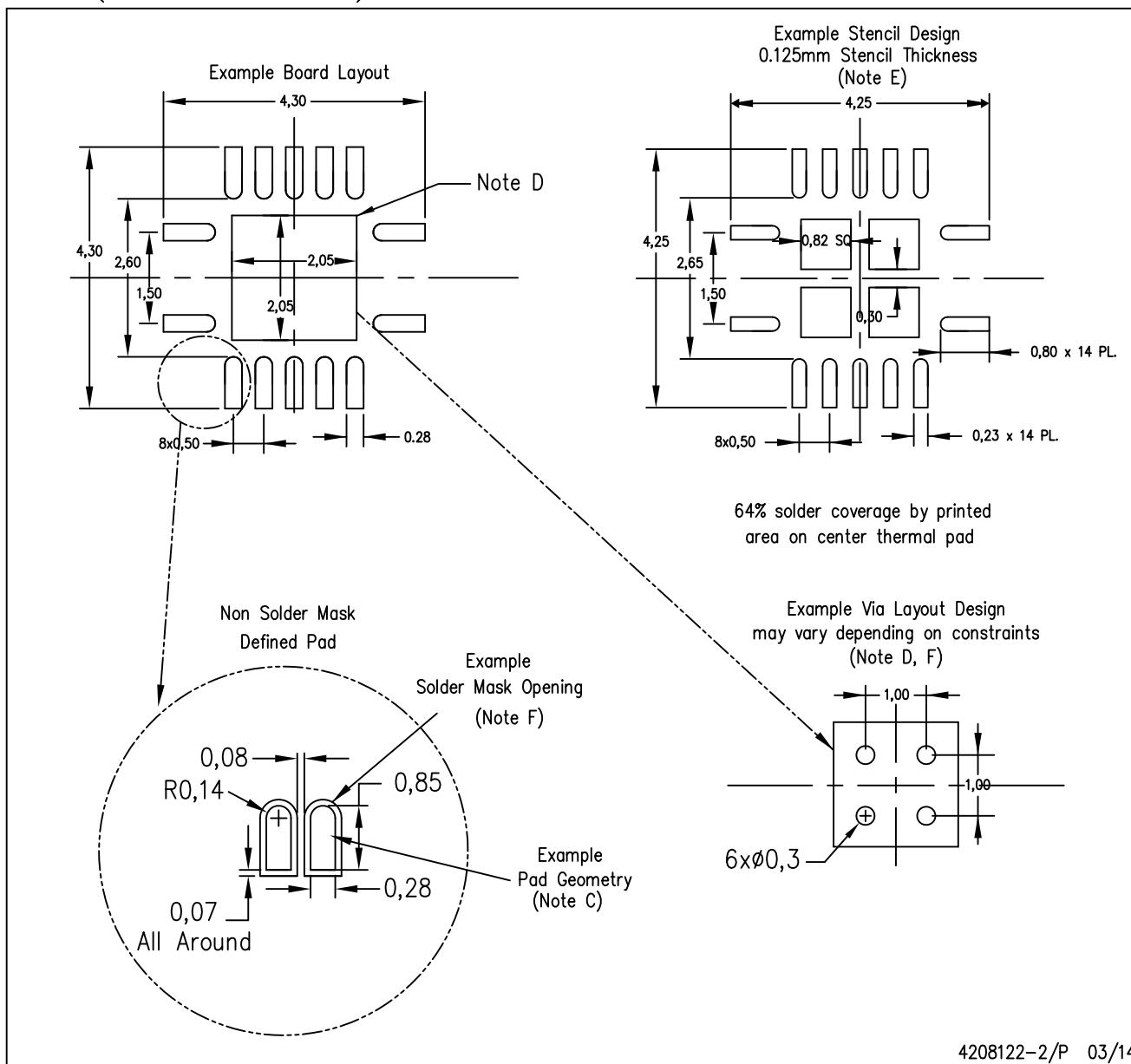
4206353-2/P 03/14

NOTE: All linear dimensions are in millimeters

## LAND PATTERN DATA

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



4208122-2/P 03/14

NOTES:

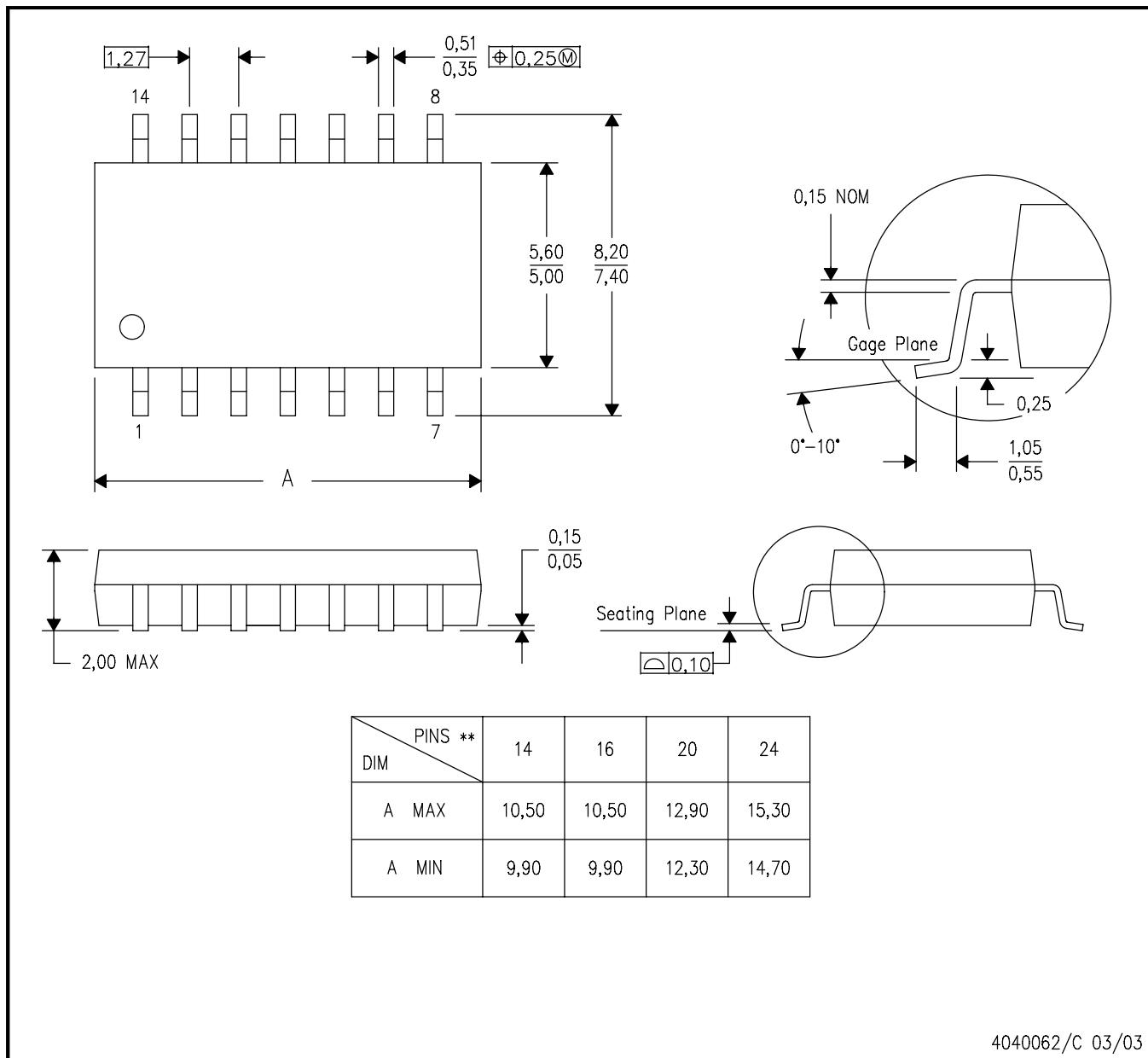
- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

## MECHANICAL DATA

## NS (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

**14-PINS SHOWN**

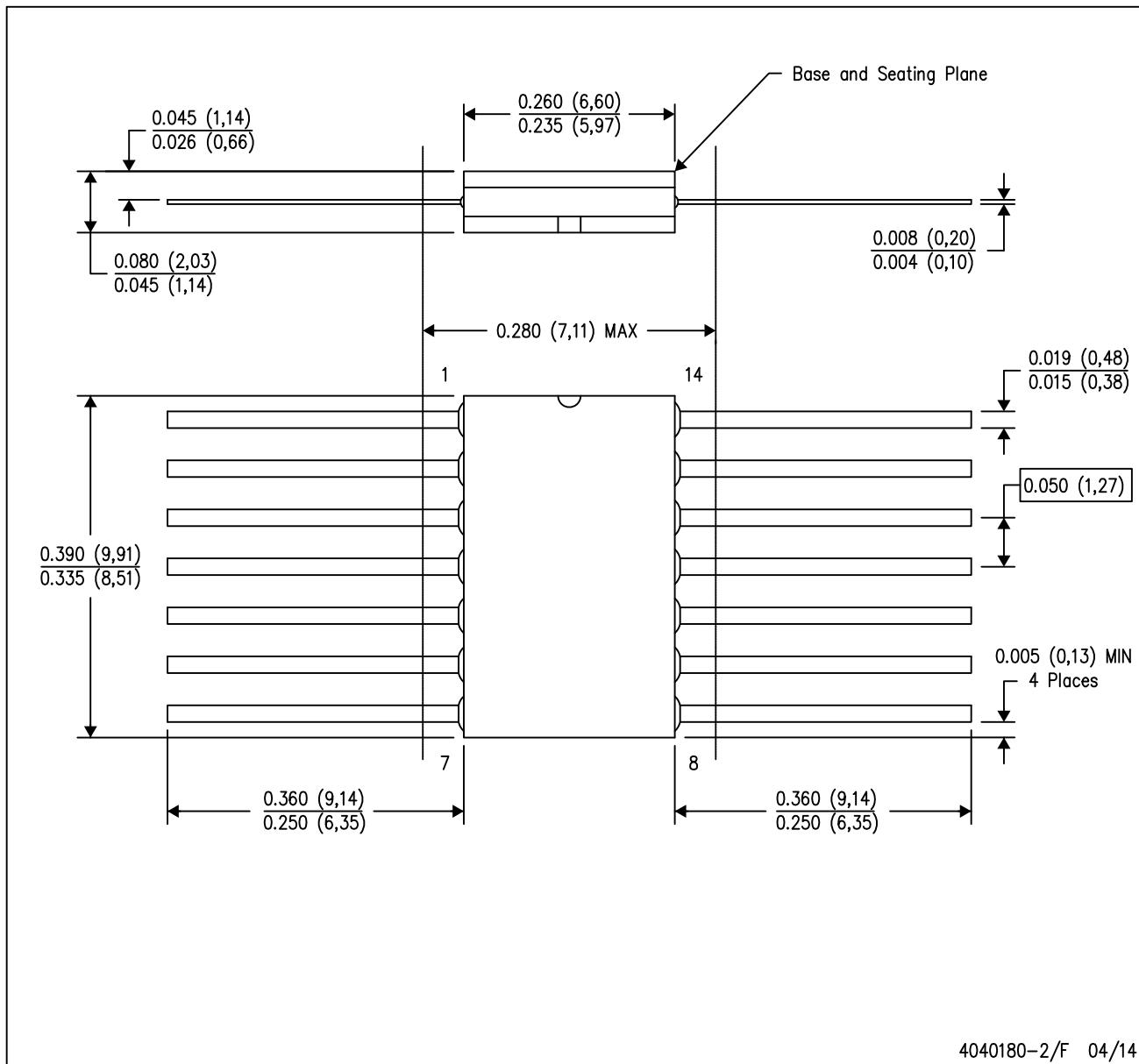


NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



4040180-2/F 04/14

NOTES:

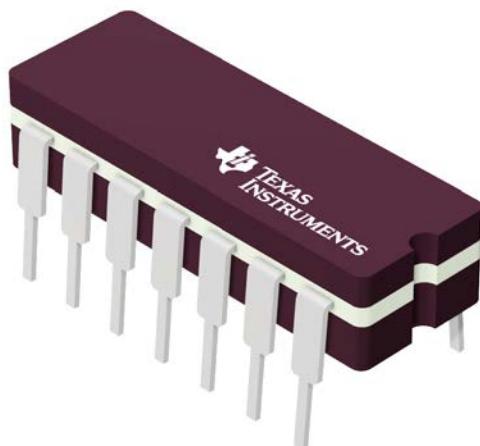
- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within MIL-STD 1835 GDFP1-F14

# GENERIC PACKAGE VIEW

**J 14**

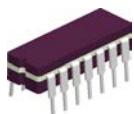
**CDIP - 5.08 mm max height**

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

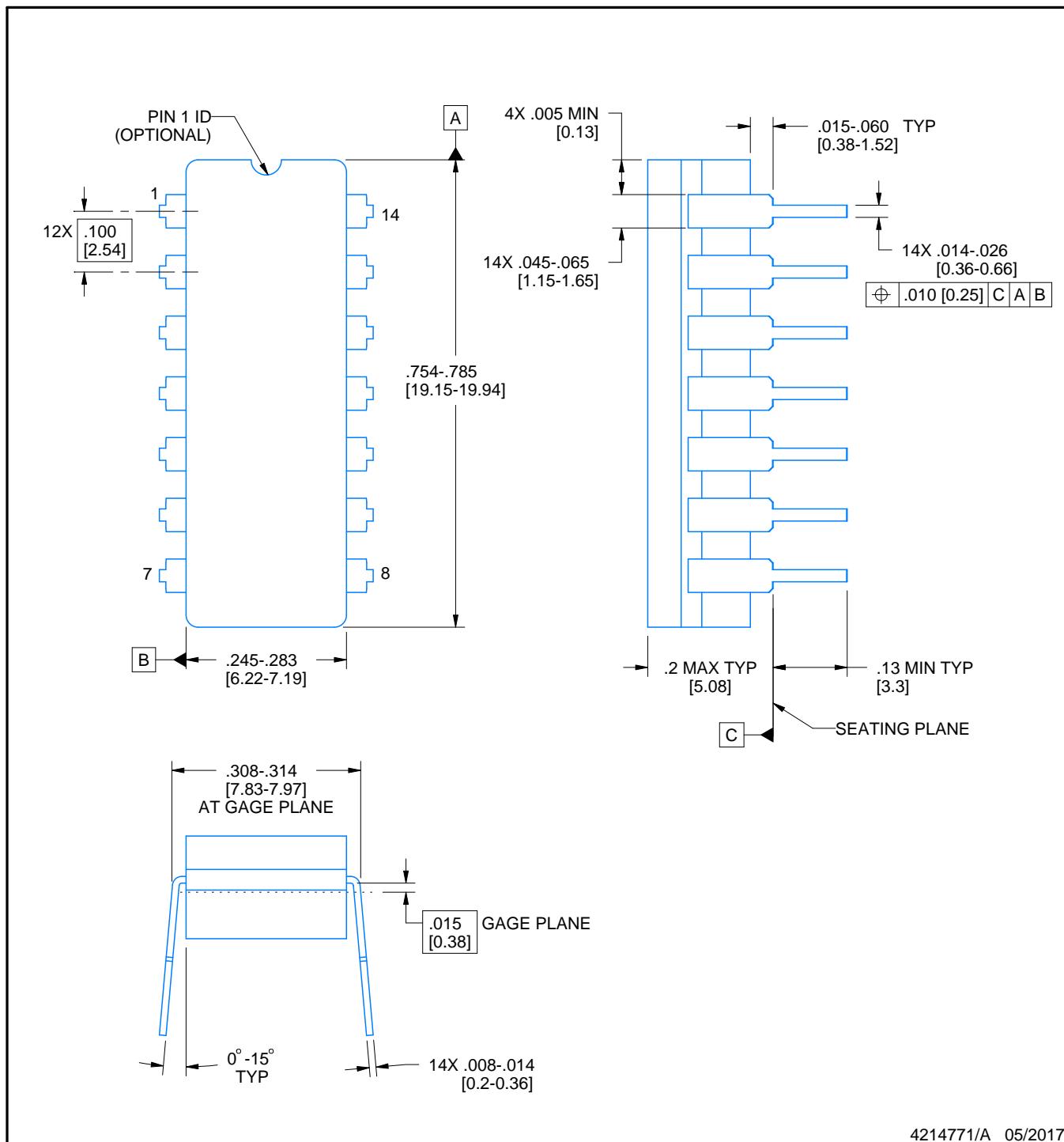


# PACKAGE OUTLINE

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

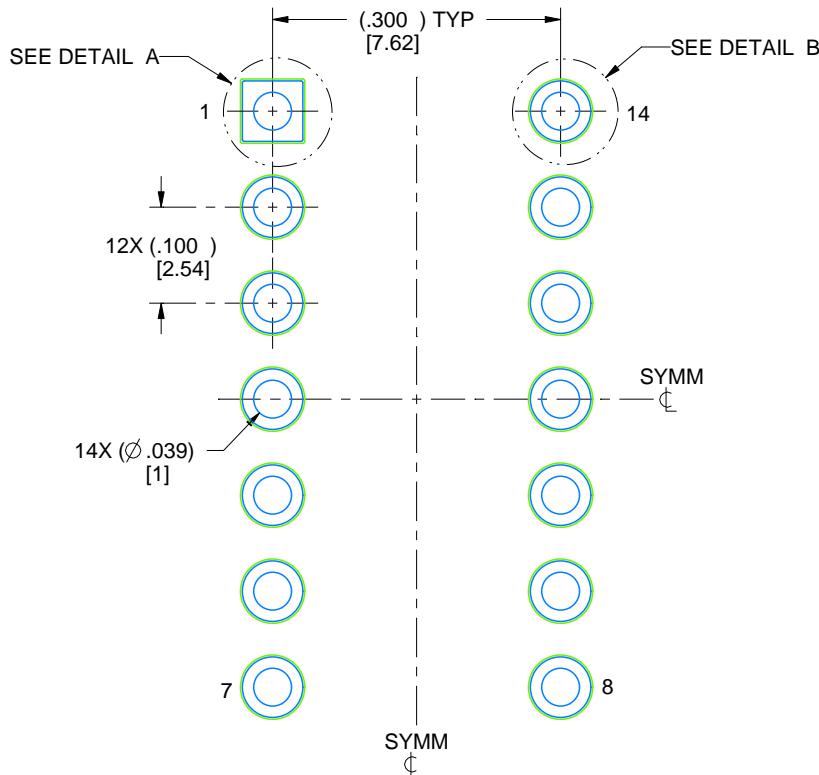
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

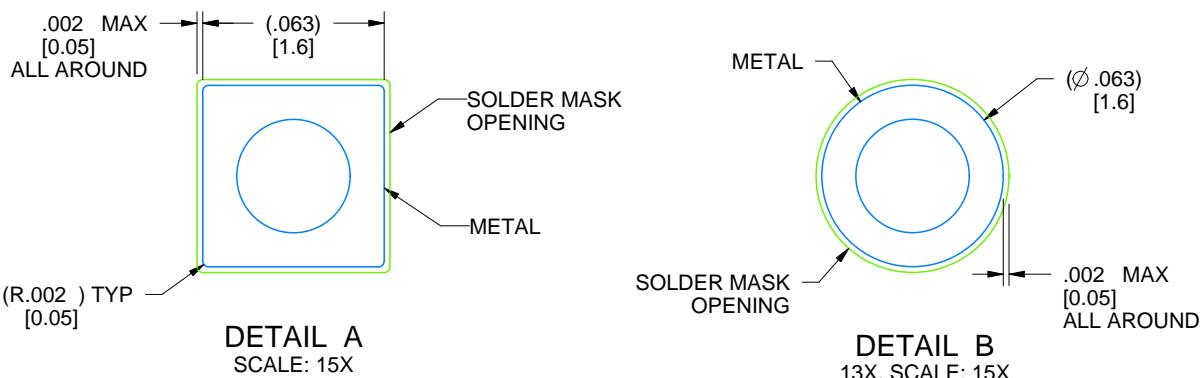
J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



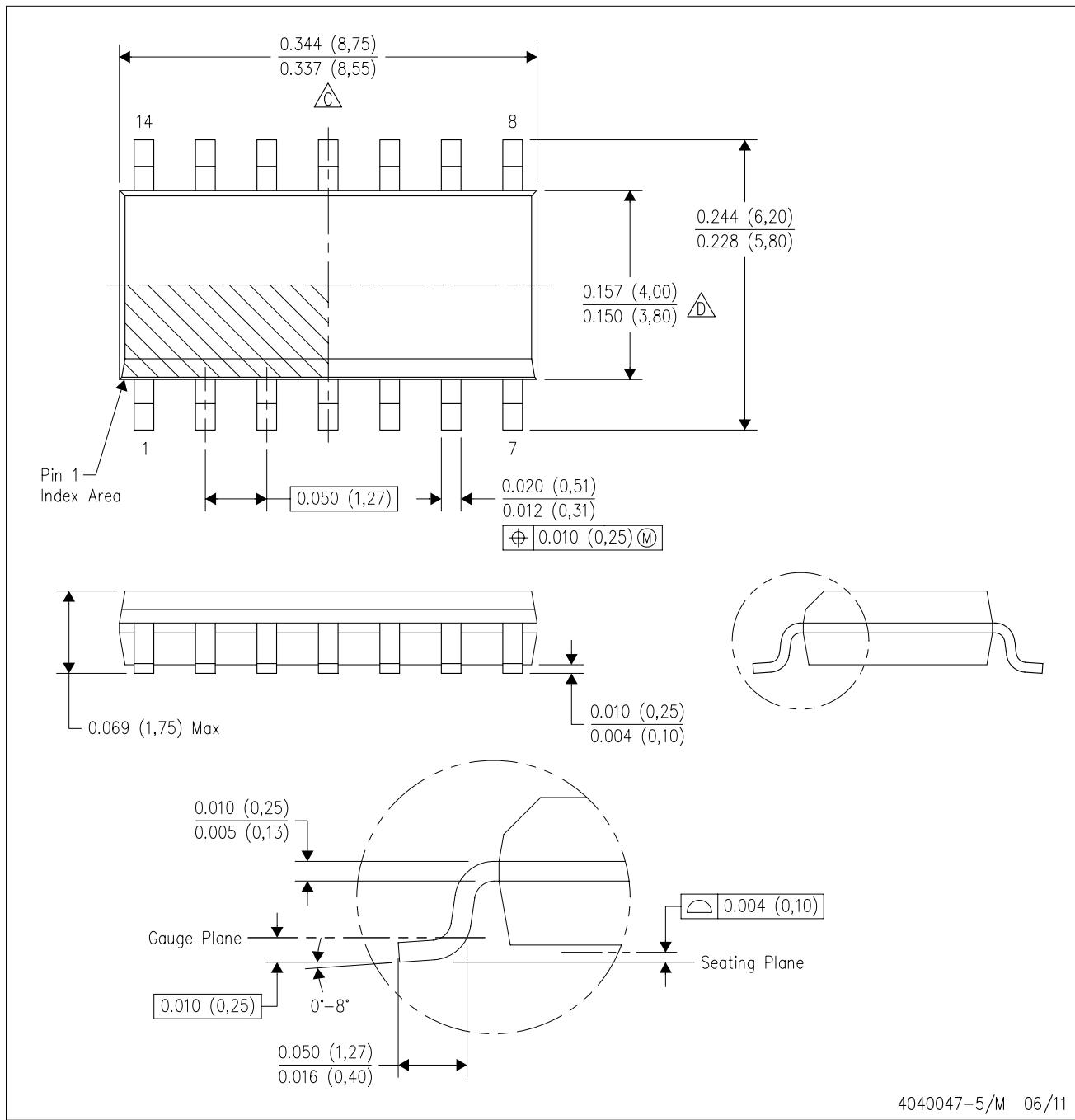
LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

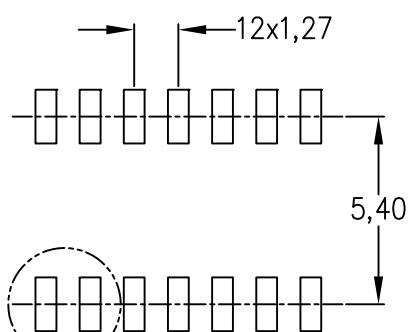
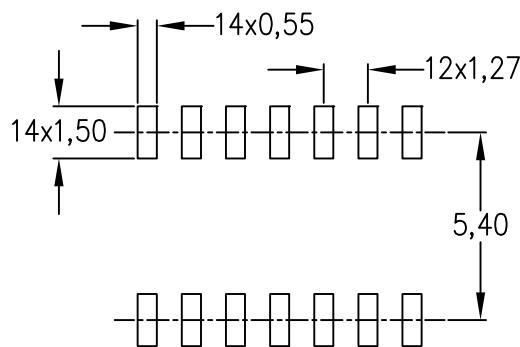
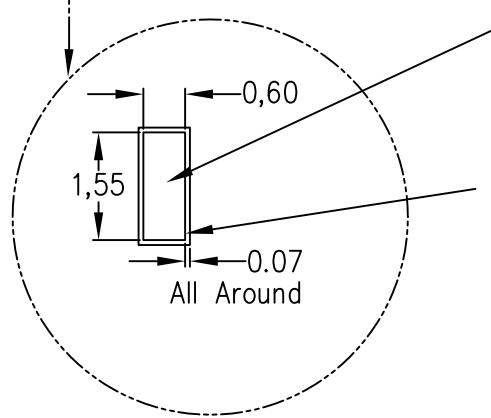
C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0.15) each side.

D Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0.43) each side.

E Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

Example Board Layout  
(Note C)Stencil Openings  
(Note D)Example  
Non Soldermask Defined PadExample  
Pad Geometry  
(See Note C)Example  
Solder Mask Opening  
(See Note E)

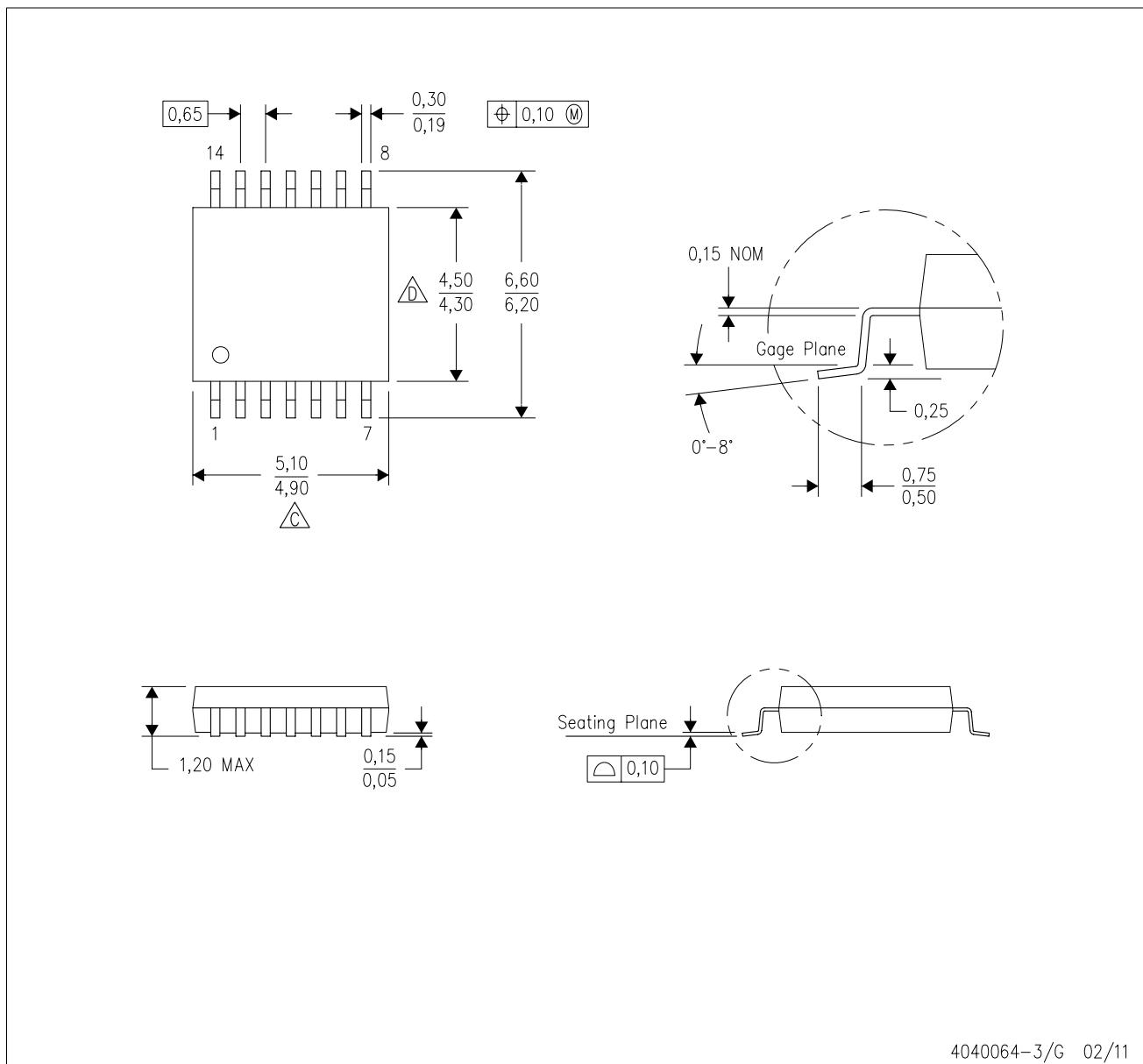
4211283-3/E 08/12

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

 C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

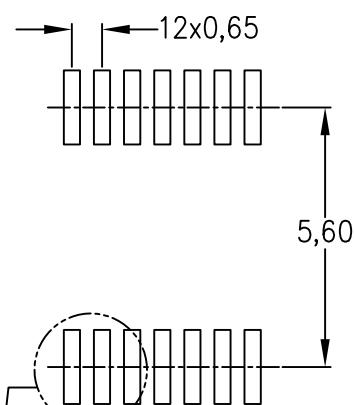
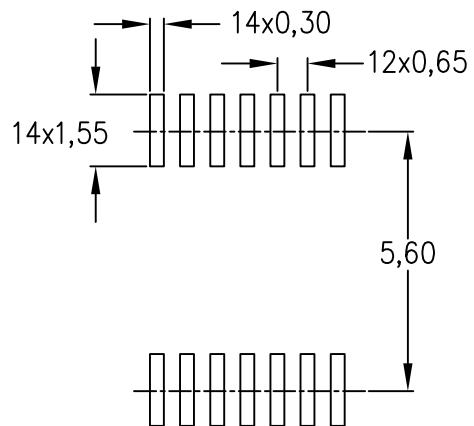
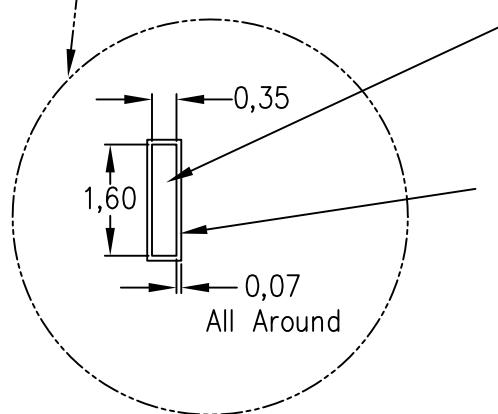
 D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153

4040064-3/G 02/11

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

Example Board Layout  
(Note C)Stencil Openings  
(Note D)Example  
Non Soldermask Defined PadExample  
Pad Geometry  
(See Note C)Example  
Solder Mask Opening  
(See Note E)

4211284-2/G 08/15

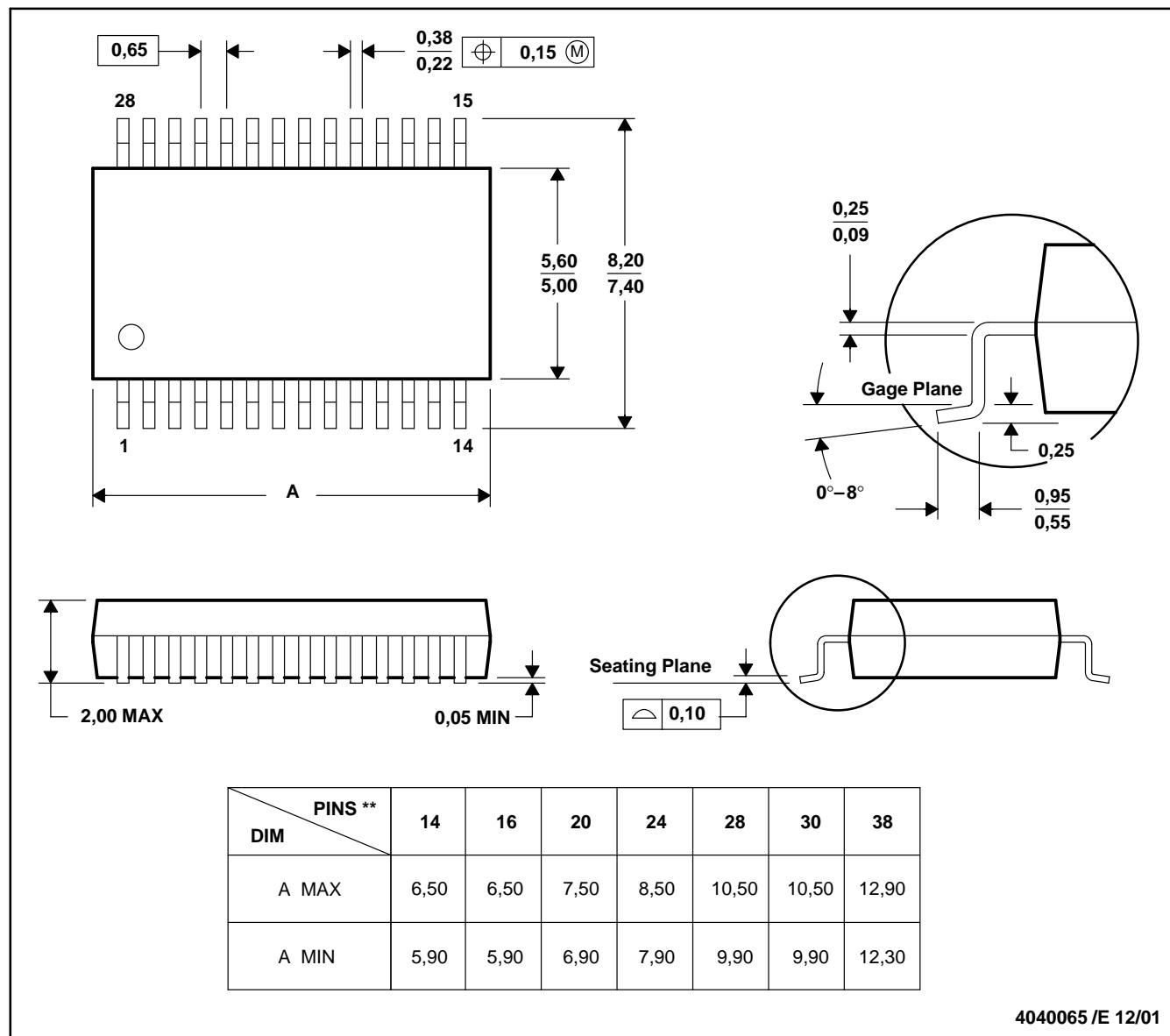
## NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

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